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## Remarks on the industrial production of FPC (15' + 8')

*Wednesday 5 February 2020 12:09 (21 minutes)*

### Abstract:

The talk will address the positive and negative experiences that RI gained during the production of FPC in large scale series (E-XFEL, LCLS-II) and small scale projects. The most critical processes and head-aches will be reflected from "behind the scenes".

The specifications do often cut the edge of achievable copper plating, TIN deposition and mechanical tolerances in a serial production and sometimes seem to be overshooting. The current development from pulsed to CW machines does raise the question, if the TTF-III coupler as a design baseline is still up to date.

### Provocative topics:

Overtight copper plating specifications

TIN deposition control (nanometers!)

Specified mechanical tolerances

Is the TTF-III coupler still up to date?

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**Session Classification:** Working Group Session